

EVAFLEX® 5-SE-G VT

한 손 결합 작업에 대응 가능한 Auto-Lock, 고온대응(125°C), 고속 전송 대응, 수직 결합, 0.5 mm Pitch, 실드 FFC/FPC



Product Specifications:

| | | |
|--------------------|-----------|--------------------------|
| Board Pitch (mm) | 0.5 | |
| Wiping Length (mm) | 1.2 | |
| Size (mm) | Height | 6.6 +/- 0.30 |
| | Width | Formula: 8.00 + (0.5*?p) |
| | Depth | 3.90 +/- 0.20 |
| Pin counts | Range | 20 - 60 |
| | Available | 20, 30, 40, 50, 60 |

Applicable FPC/FFC:

| | |
|------------------------|------------------------------------|
| FPC/FFC Type | Shielded FFC, Non-shielded FFC/FPC |
| FPC/FFC Contact Point | Signal contact tail side |
| FPC/FFC Thickness (mm) | 0.30 +/- 0.03 |

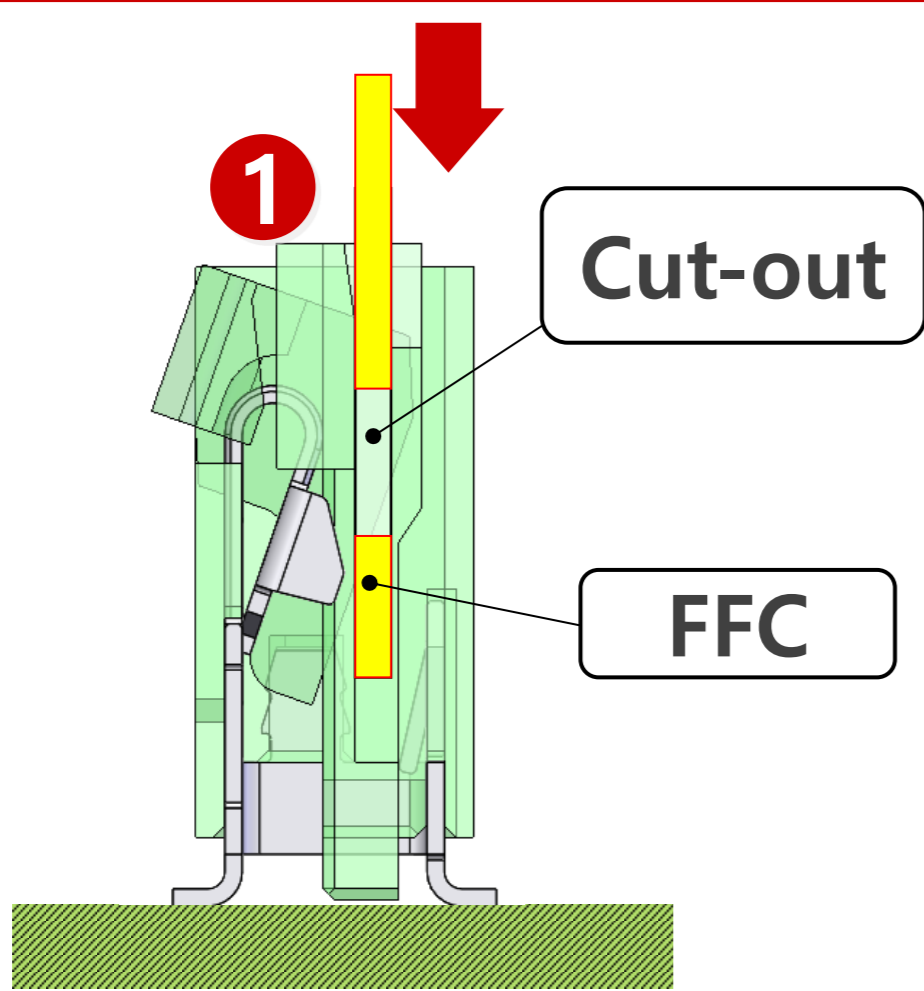
Applicable Standards (Reference Only):

eDP (2.7 Gbps) V-By-One HS 1.4 (4 Gbps)
USCAR II Vibration & Shock V1

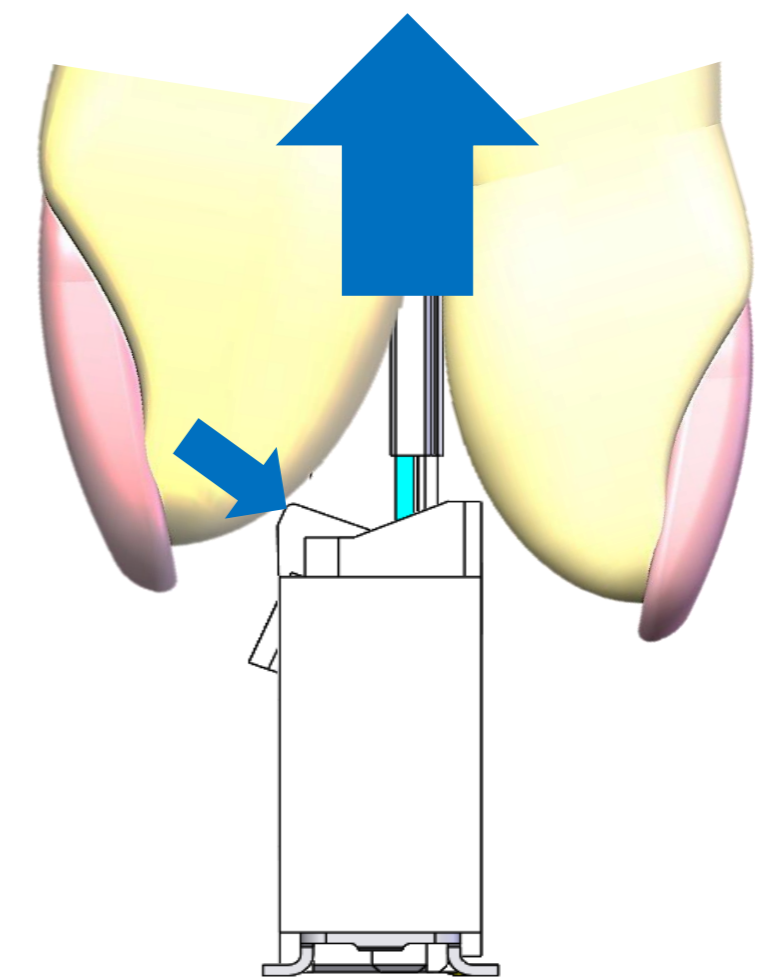
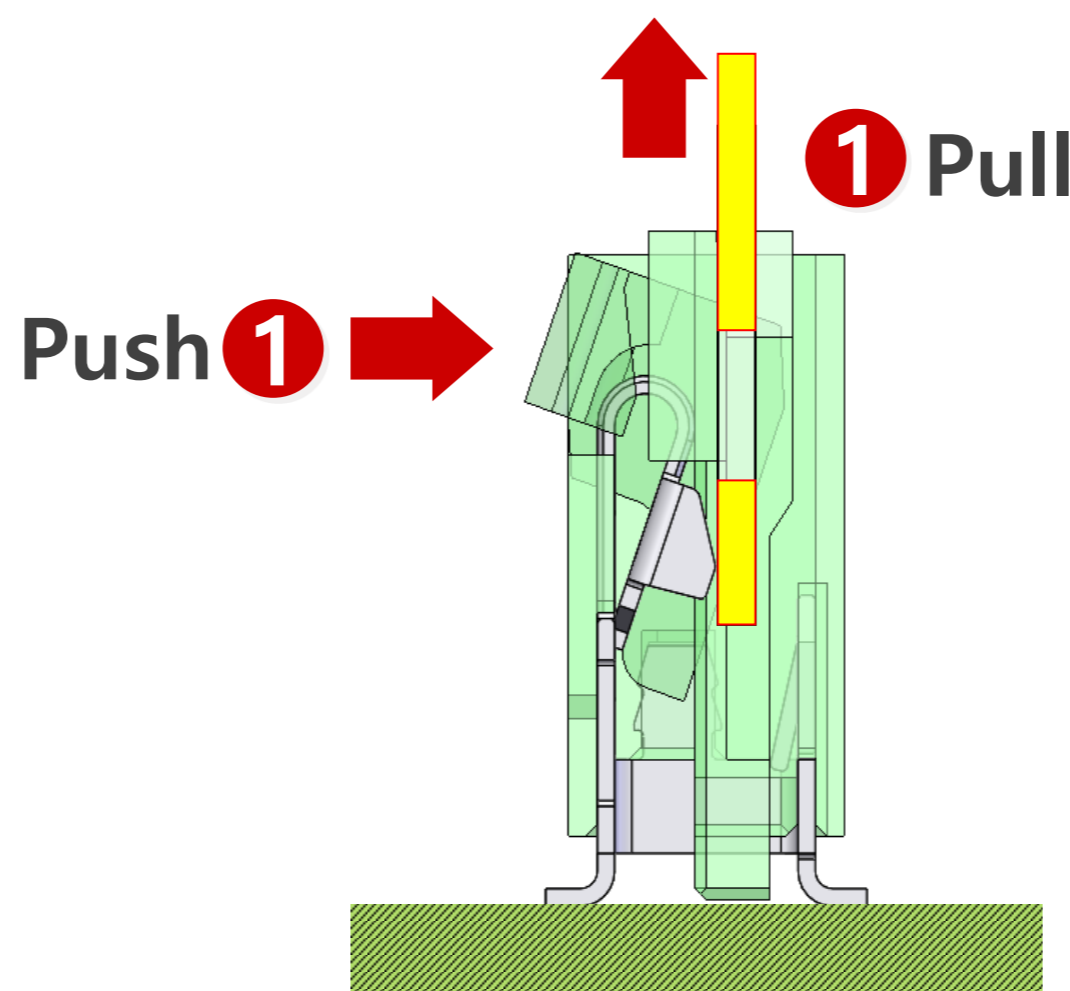
*기재가 되어있지 않은 핀 수의 대응 여부에 대해서는 문의해 부탁드립니다.

▶ 한 손으로 탈착 작업이 가능한 Auto-Lock 디자인, 수작업 또는 로봇에 의한 조립 작업에 최적

One action FFC체결



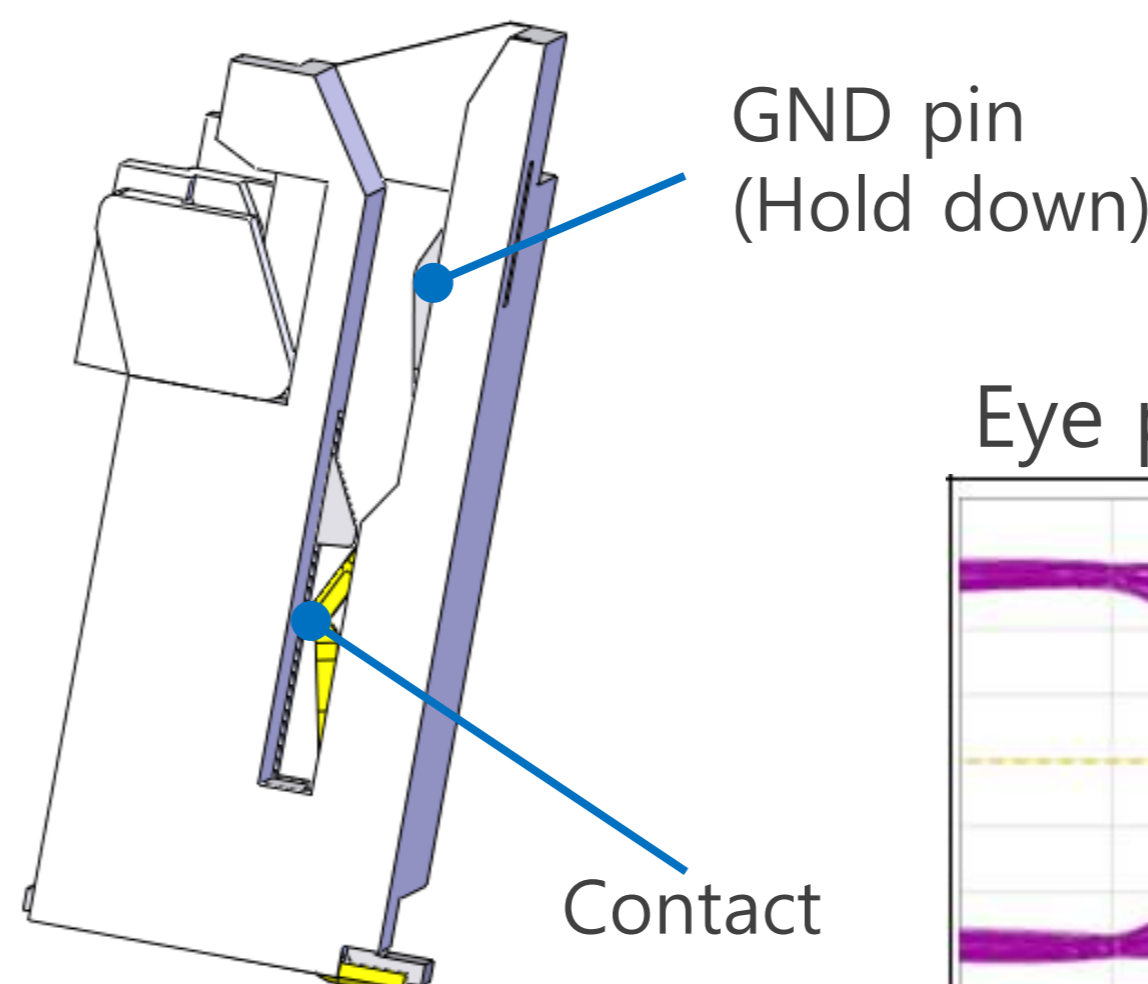
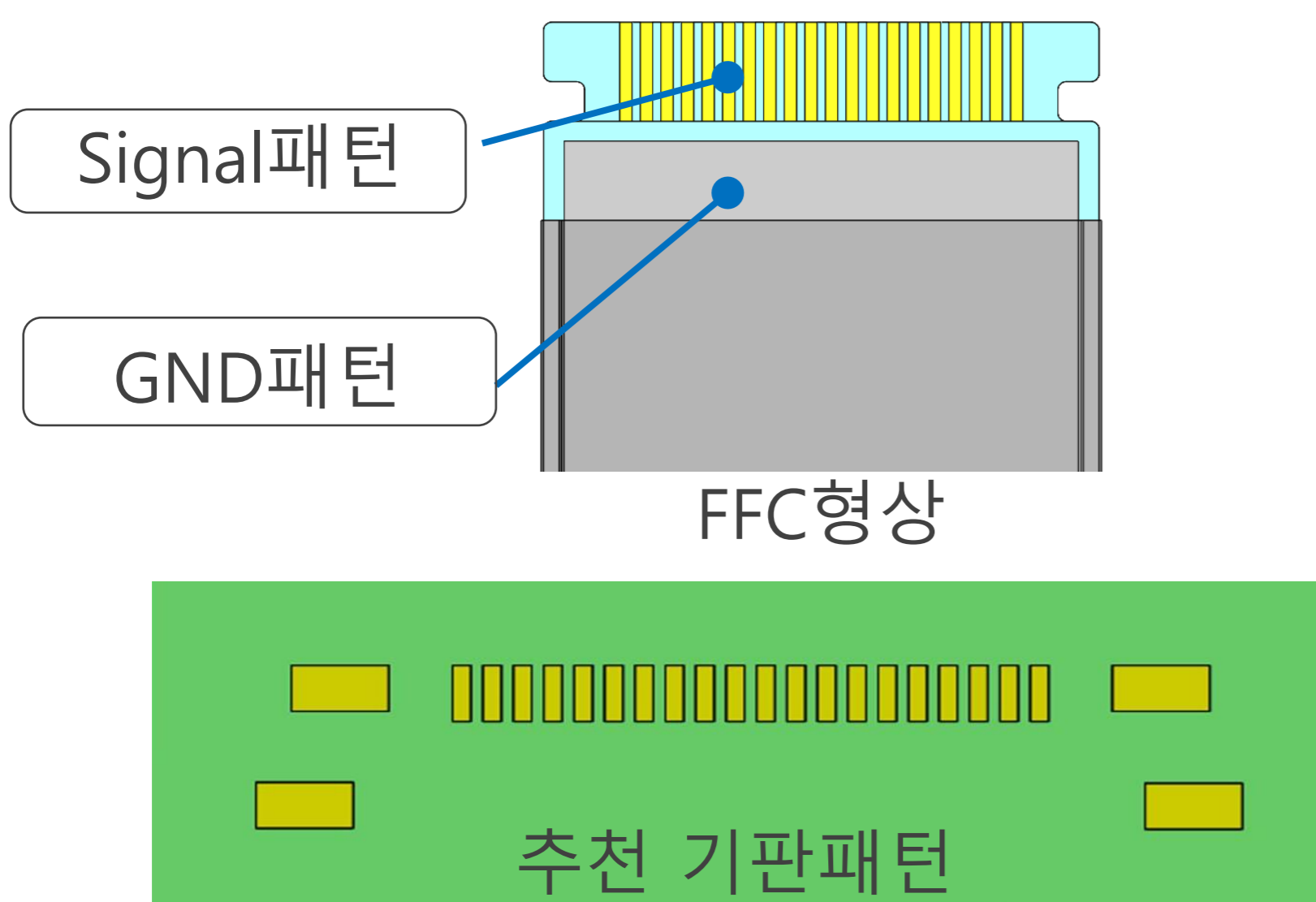
One action FFC발거



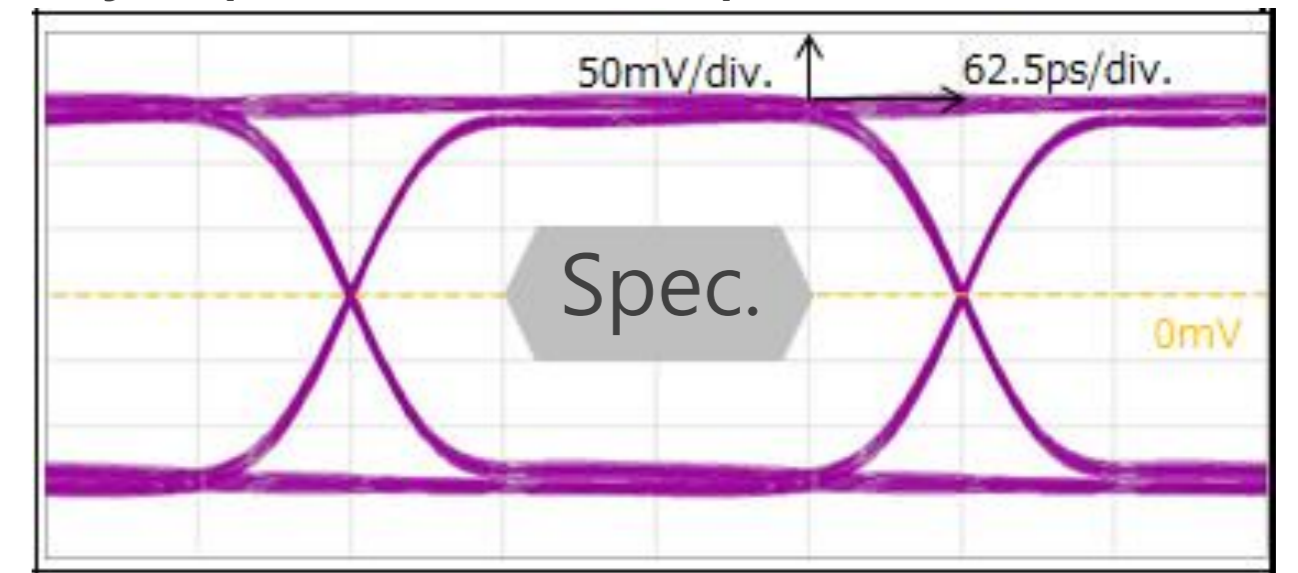
FFC를 잡음과 동시에 Lock해제 동작이 가능하도록 하였습니다

▶ 그라운드 단자를 내장한 고속 전송 설계(4+ Gbps V-by-One® HS)

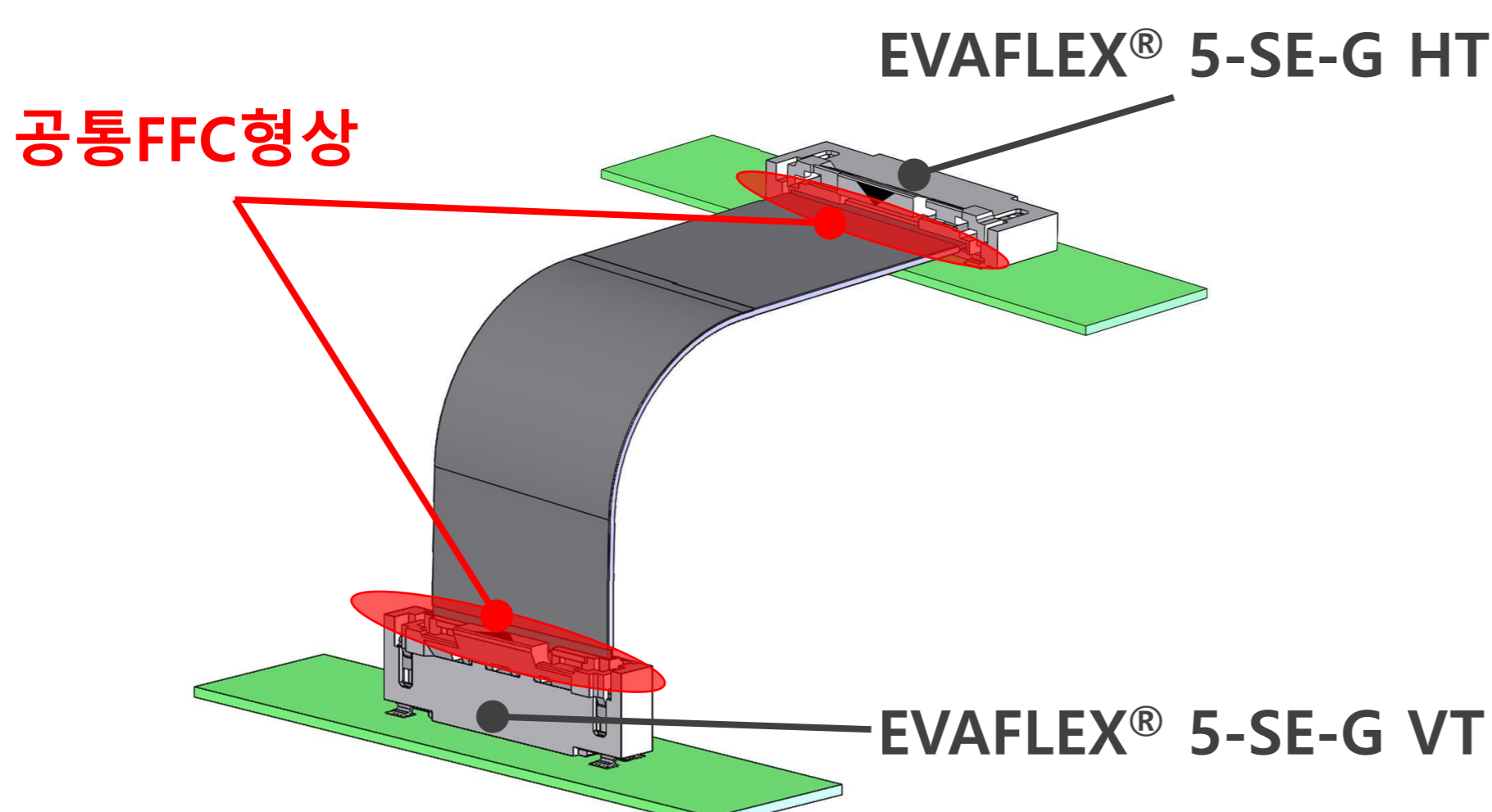
Hold down을 GND로 사용 가능.
전송속도 Target : 4+ Gbps (V-by-One® HS)



Eye pattern 4 Gbps (actual)



▶ 동일한 FFC가 사용 가능한 Horizontal 타입(EVAFLEX® 5-SE-G HT) 옵션도 보유



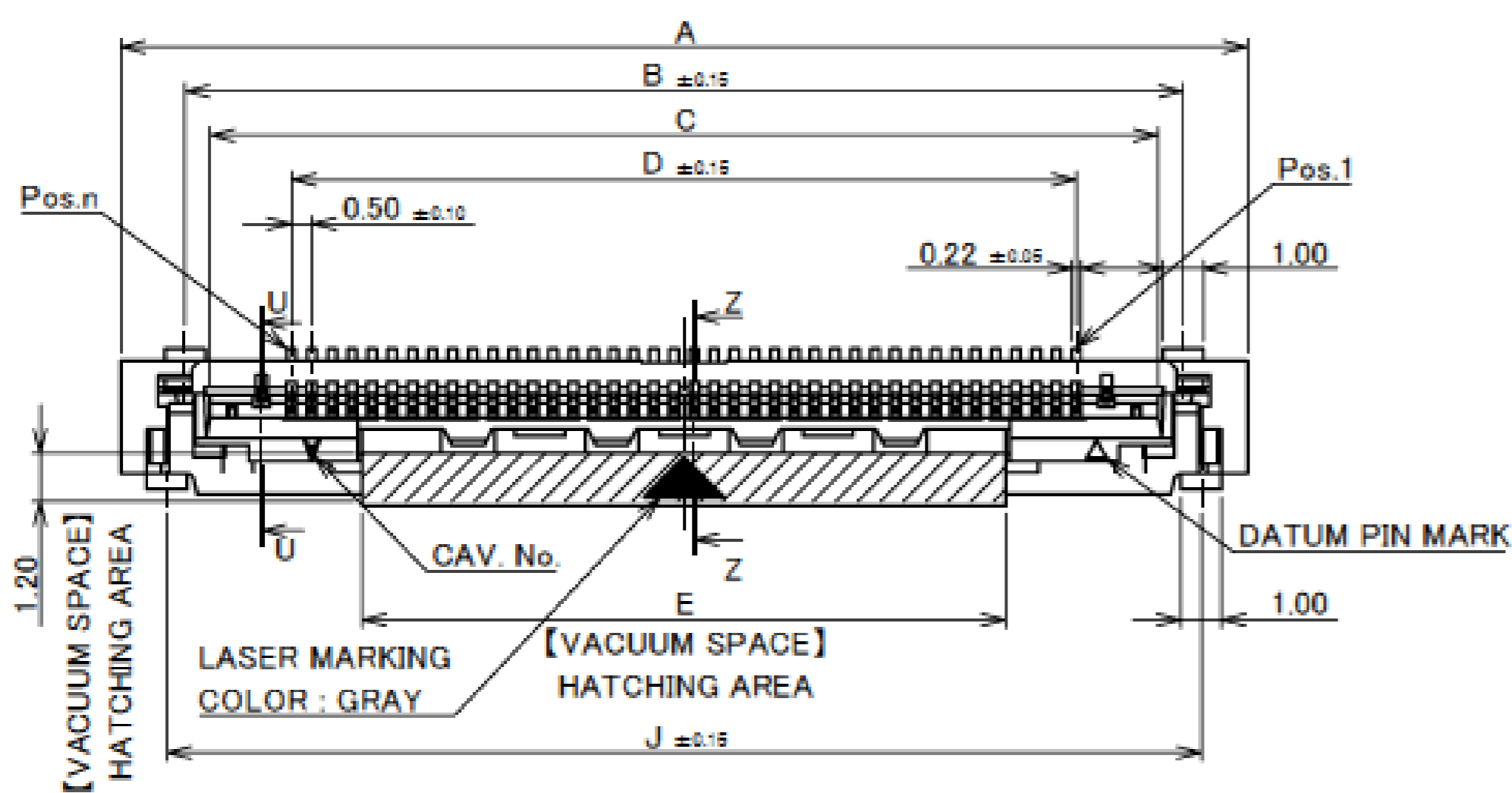
| | EVAFLEX® 5-SE-G HT |
|-------------|--------------------|
| Height (mm) | 3.65 +/- 0.1 |
| Depth (mm) | 7.0 |



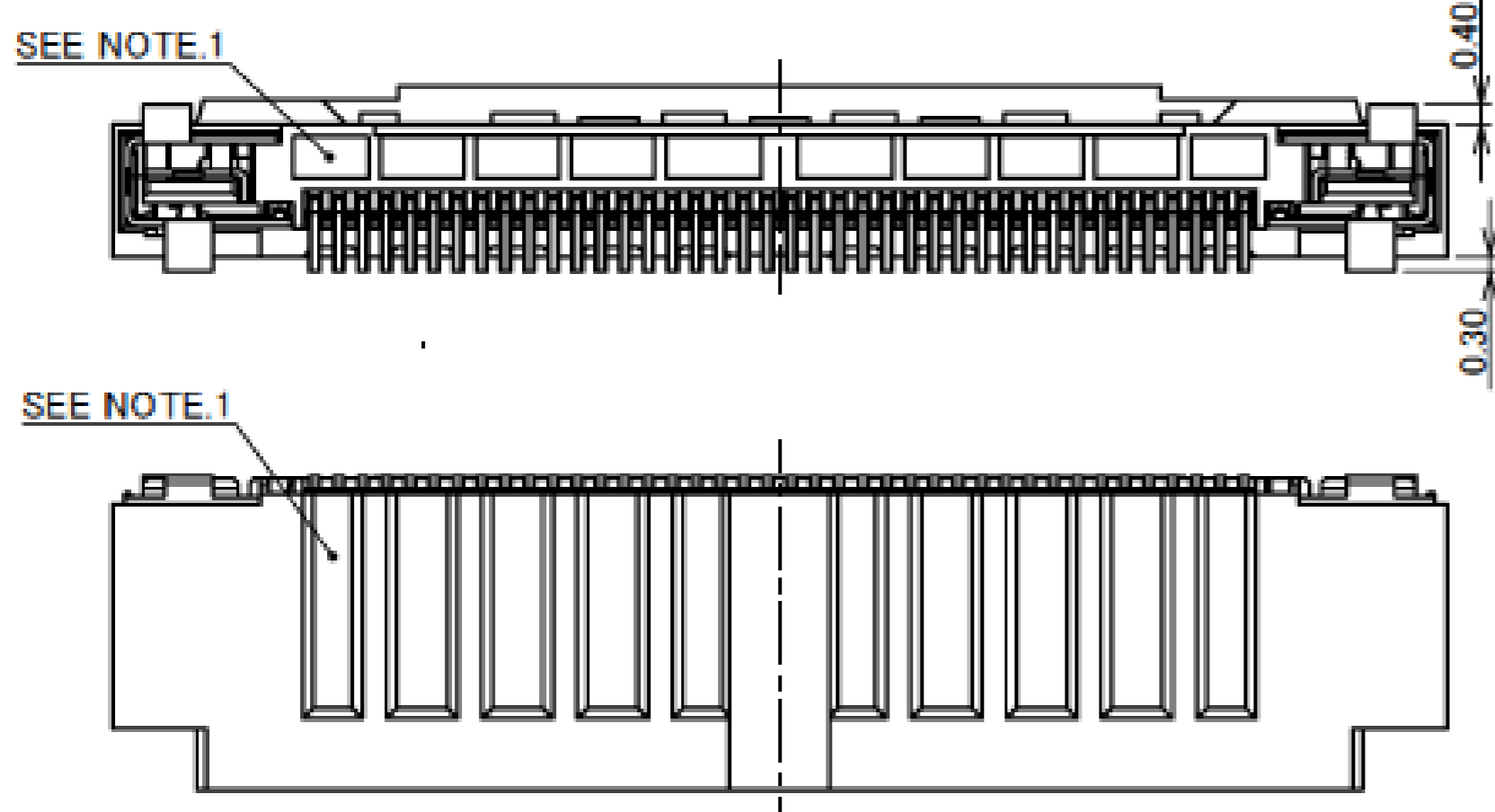
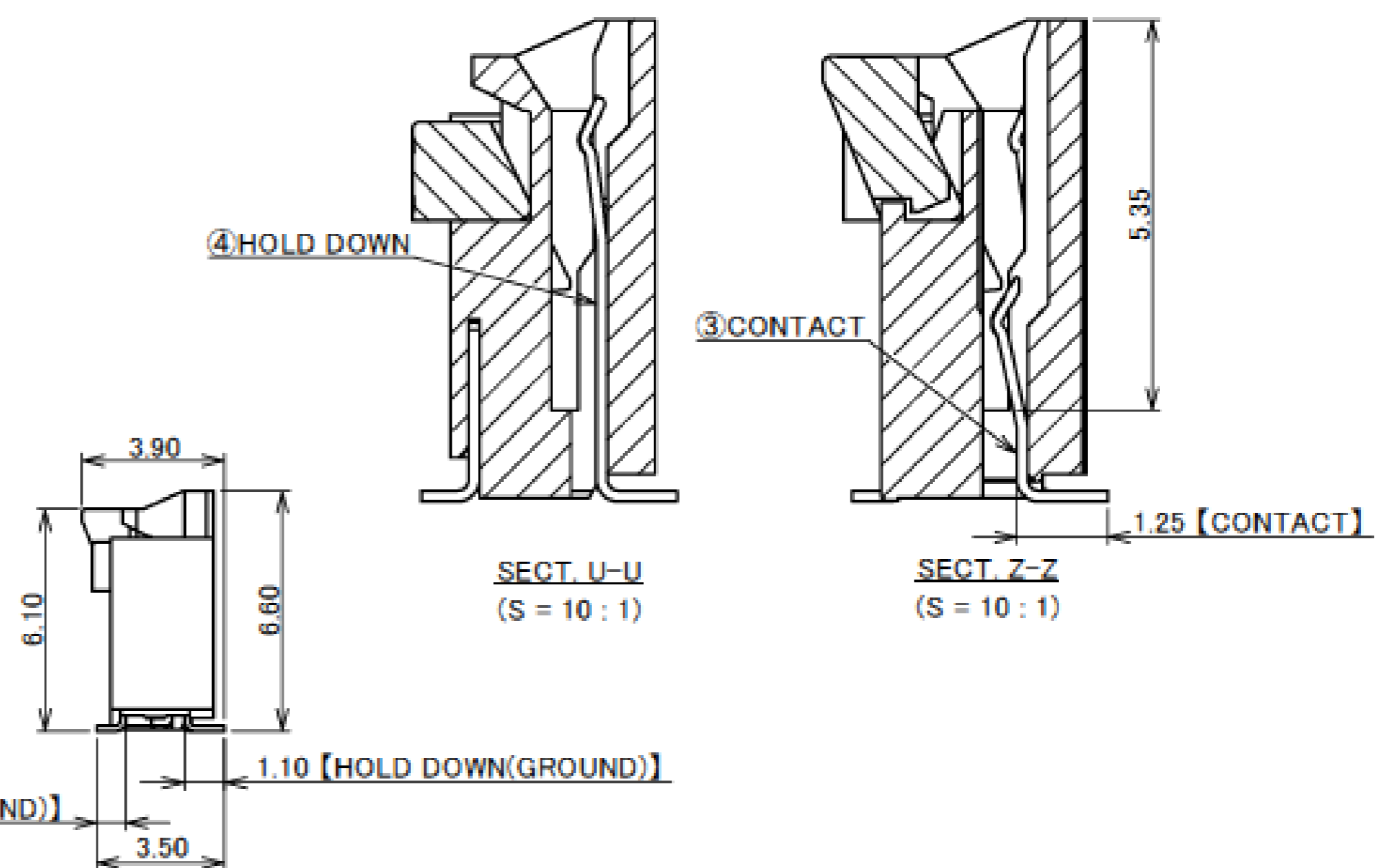
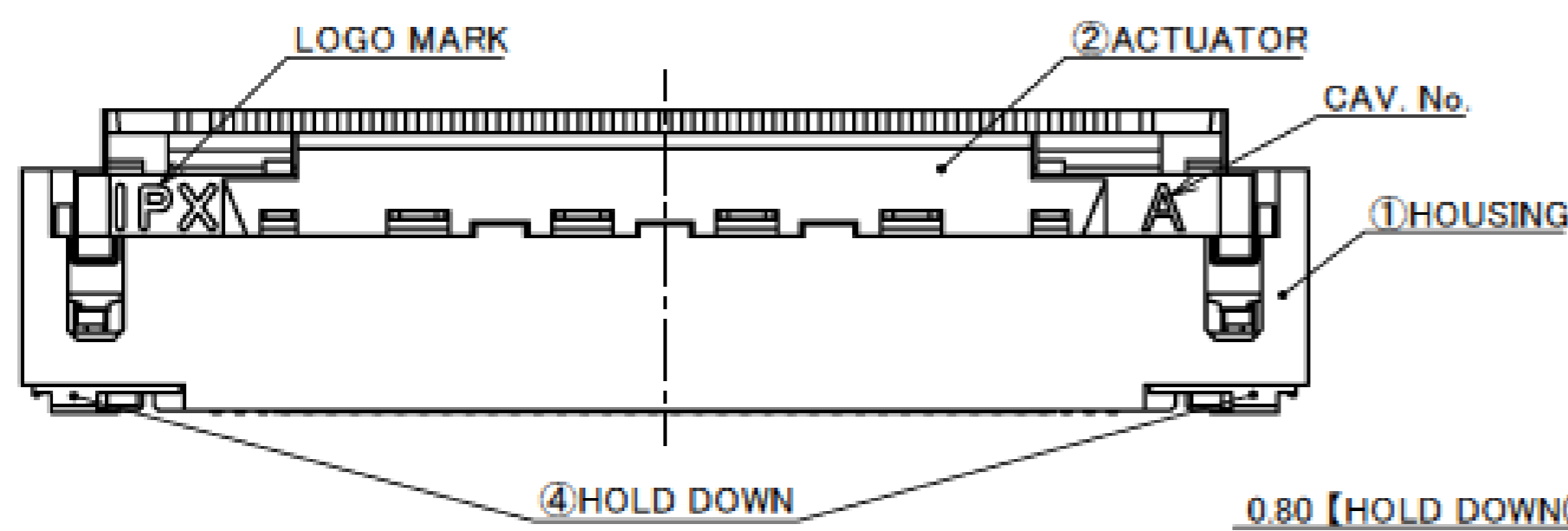
Component Parts Details

Connector Assembly

Recommended P/N 20799-0**E-01



| PART No. | A | B | C | D | E | J |
|---------------|-------|-------|-------|-------|-------|-------|
| 20799-020E-01 | 18.00 | 14.80 | 13.56 | 9.50 | 6.00 | 15.70 |
| 20799-030E-01 | 23.00 | 19.80 | 18.56 | 14.50 | 11.00 | 20.70 |
| 20799-040E-01 | 28.00 | 24.80 | 23.56 | 19.50 | 16.00 | 25.70 |
| 20799-050E-01 | 33.00 | 29.80 | 28.56 | 24.50 | 21.00 | 30.70 |
| 20799-060E-01 | 38.00 | 34.80 | 33.56 | 29.50 | 26.00 | 35.70 |



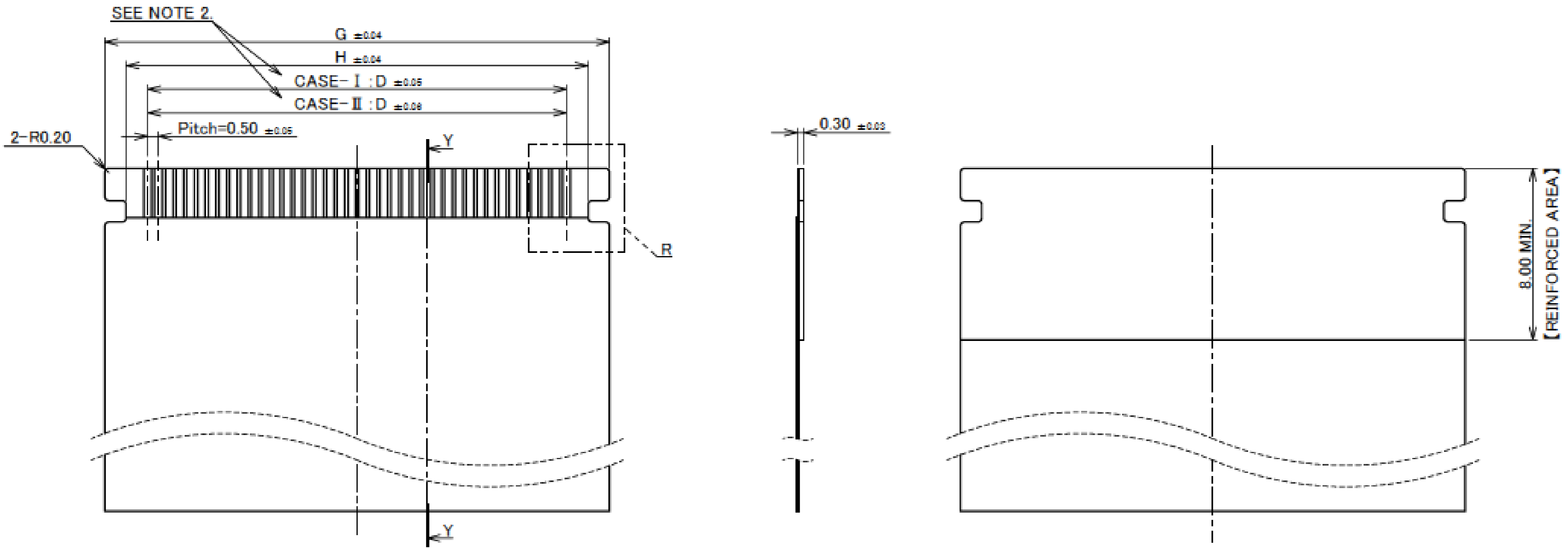
NOTES.
1. DENT SHAPE SHOWN ON DRAWING IS JUST FOR REFERENCE.
DENT SHAPE AND QUANTITY MIGHT CHANGE FROM DIFFERENT PIN COUNT AND DIFFERENT TOOLING.

| NO. | DISCRIPTION | MATERIAL | FINISH , REMARKS |
|-----|-------------|--------------|--|
| 4 | HOLD DOWN | CORSON ALLOY | SOLDERING AREA : Au 0.03µm MIN. OVER Ni 1.00µm MIN. |
| 3 | CONTACT | CORSON ALLOY | CONTACT AREA AND SOLDERING AREA : Au 0.03µm MIN. OVER Ni 1.00µm MIN. |
| 2 | ACTUATOR | LCP | UL94V-0, BEIGE |
| 1 | HOUSING | LCP | UL94V-0, BEIGE |

Connector Assembly

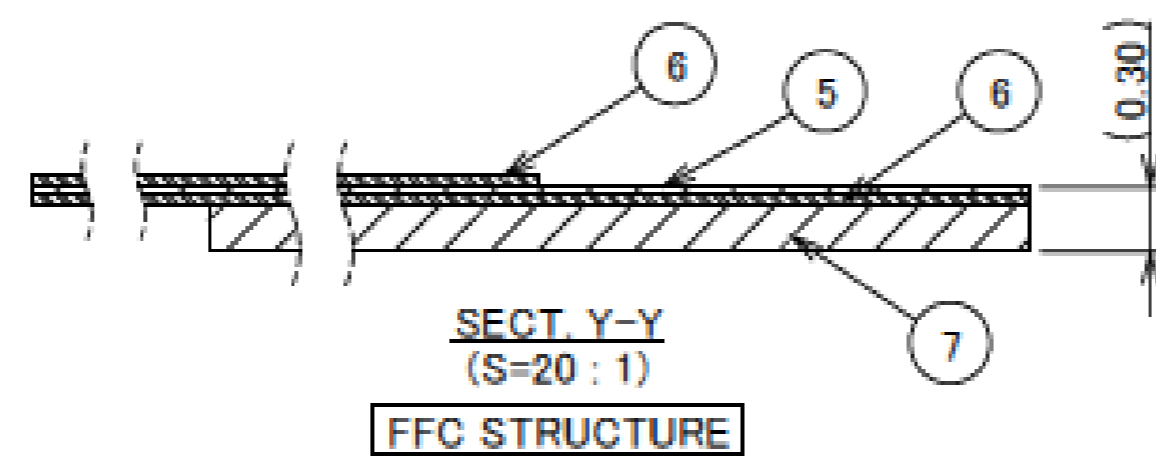
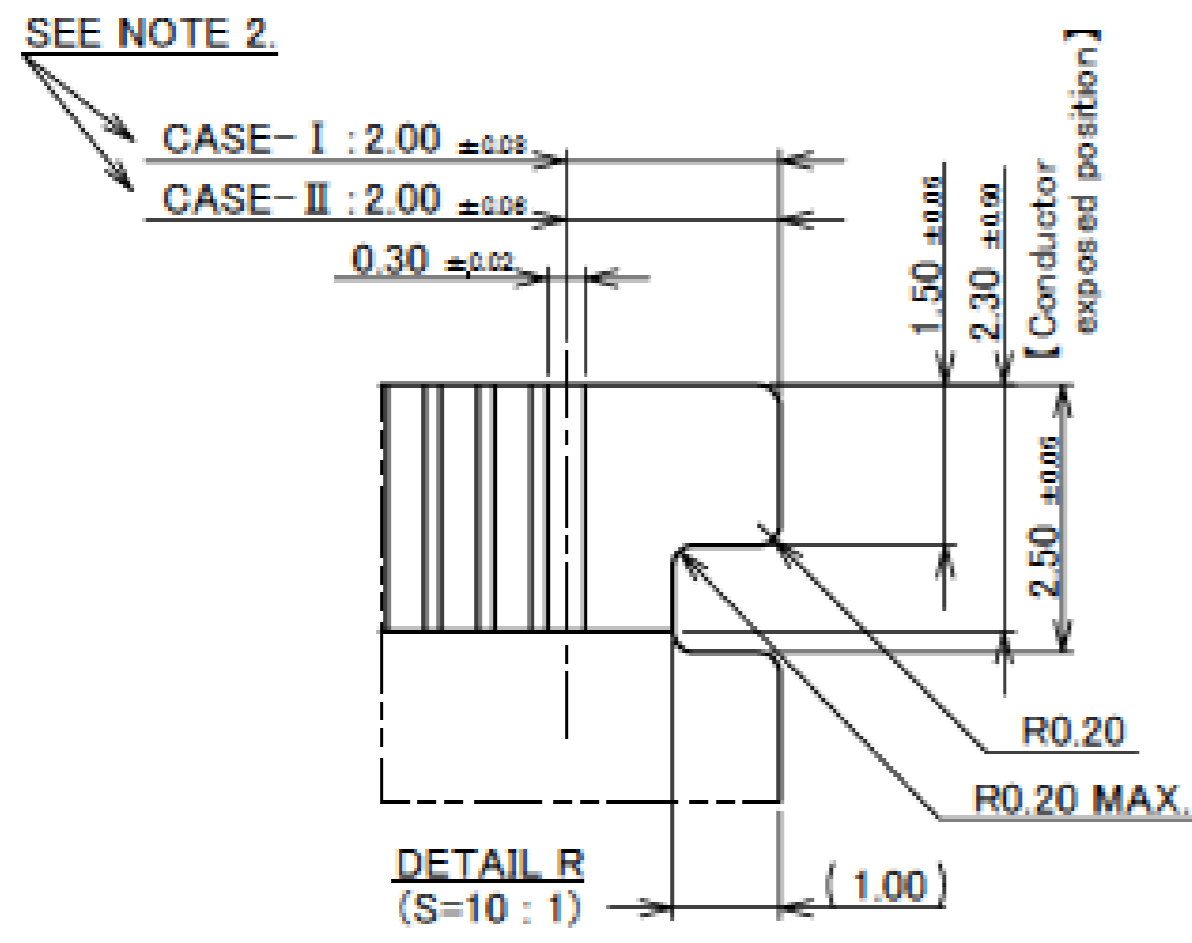
| PART No. | D | G | H |
|---------------|-------|-------|-------|
| 20799-020E-01 | 9.50 | 13.50 | 11.50 |
| 20799-030E-01 | 14.50 | 18.50 | 16.50 |
| 20799-040E-01 | 19.50 | 23.50 | 21.50 |
| 20799-050E-01 | 24.50 | 28.50 | 26.50 |
| 20799-060E-01 | 29.50 | 33.50 | 31.50 |

RECOMMENDED FFC LAYOUT 【NON SHIELDED TYPE】



NOTES.
2. MANUFACTURE CASE- I or II
3. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.

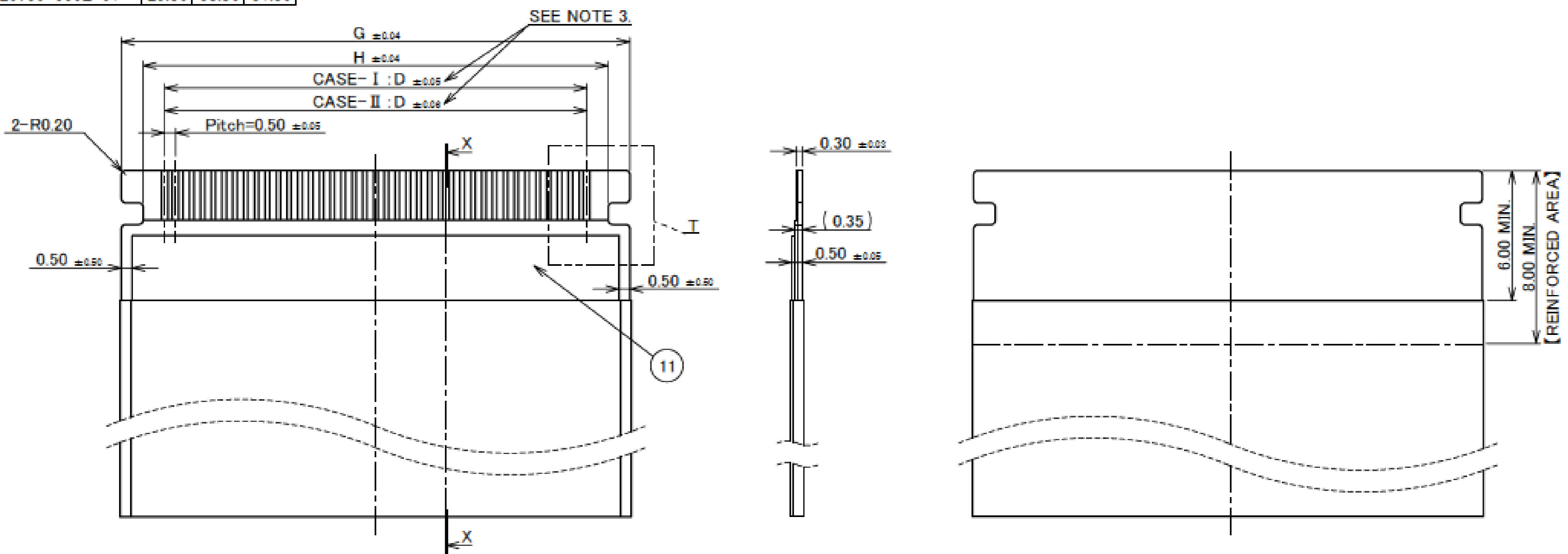
| NO. | COMPONENTS | MATERIAL | FINISH |
|-----|-----------------|--------------|--|
| 7 | REINFORCED TAPE | ARBITRARY | |
| 6 | INSULATION FILM | ARBITRARY | |
| 5 | CONDUCTOR | COPPER ALLOY | CONTACT AREA : Au 0.05 μm MIN. OVER Ni 0.5 μm MIN. |



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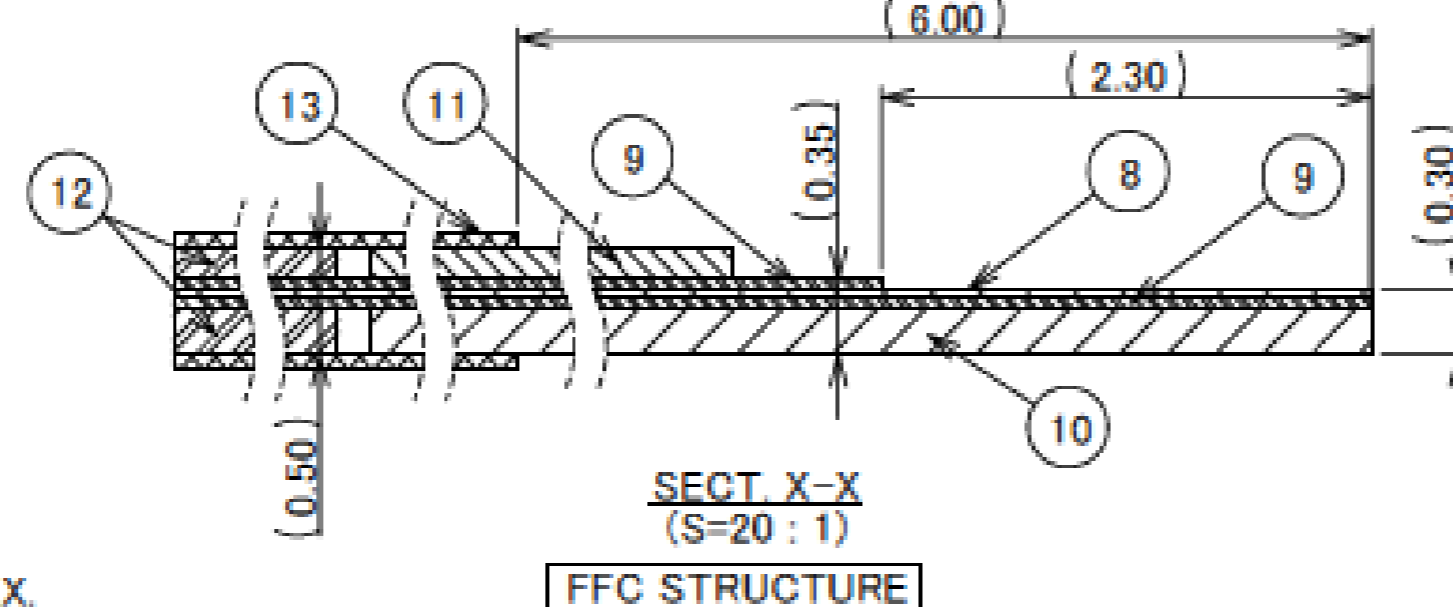
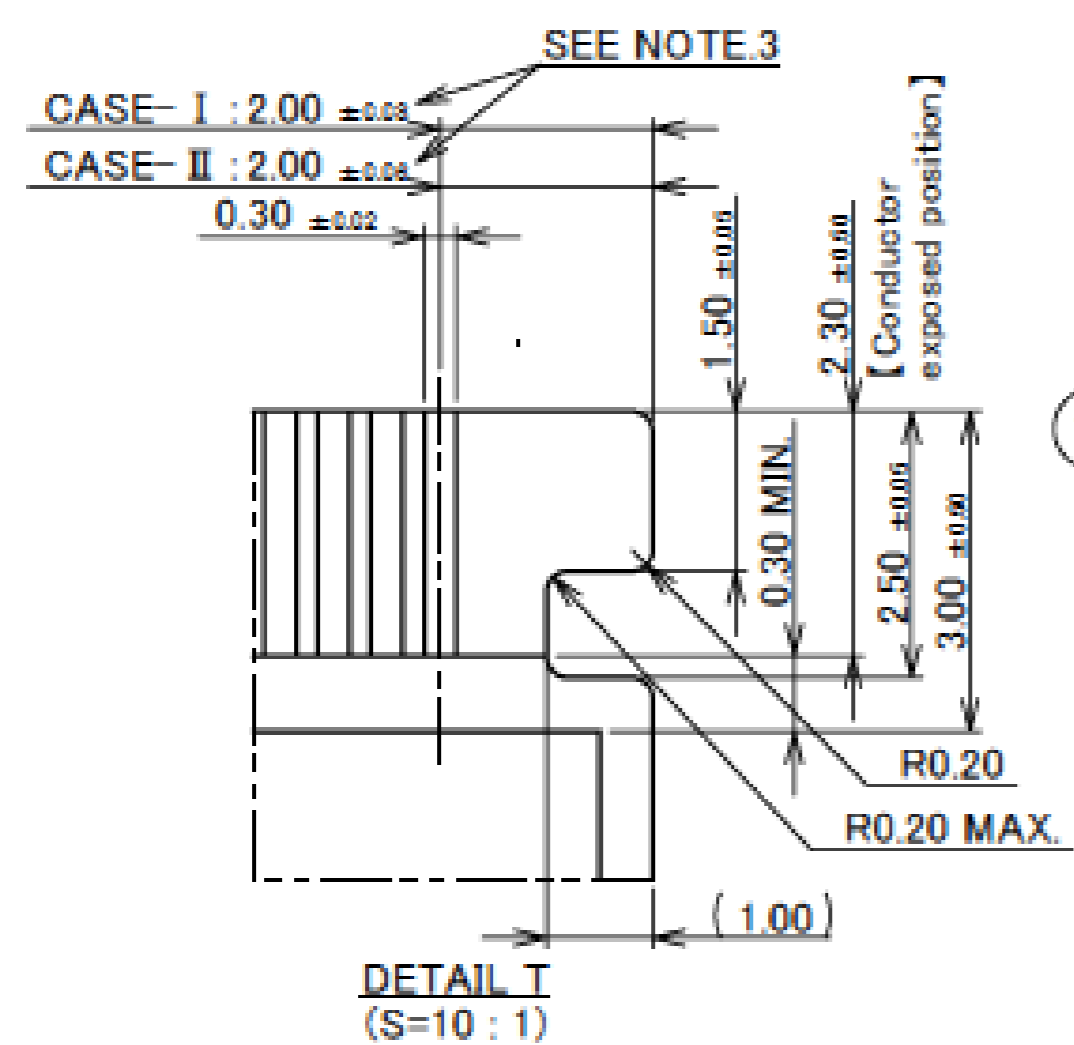
| PART No. | D | G | H |
|---------------|-------|-------|-------|
| 20799-020E-01 | 9.50 | 13.50 | 11.50 |
| 20799-030E-01 | 14.50 | 18.50 | 16.50 |
| 20799-040E-01 | 19.50 | 23.50 | 21.50 |
| 20799-050E-01 | 24.50 | 28.50 | 26.50 |
| 20799-060E-01 | 29.50 | 33.50 | 31.50 |

RECOMMENDED FFC LAYOUT 【SHIELDED TYPE】



NOTES.
4. MANUFACTURE CASE- I or II
5. DIFFERENTIAL IMPEDANCE : 100±10Ω
6. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.

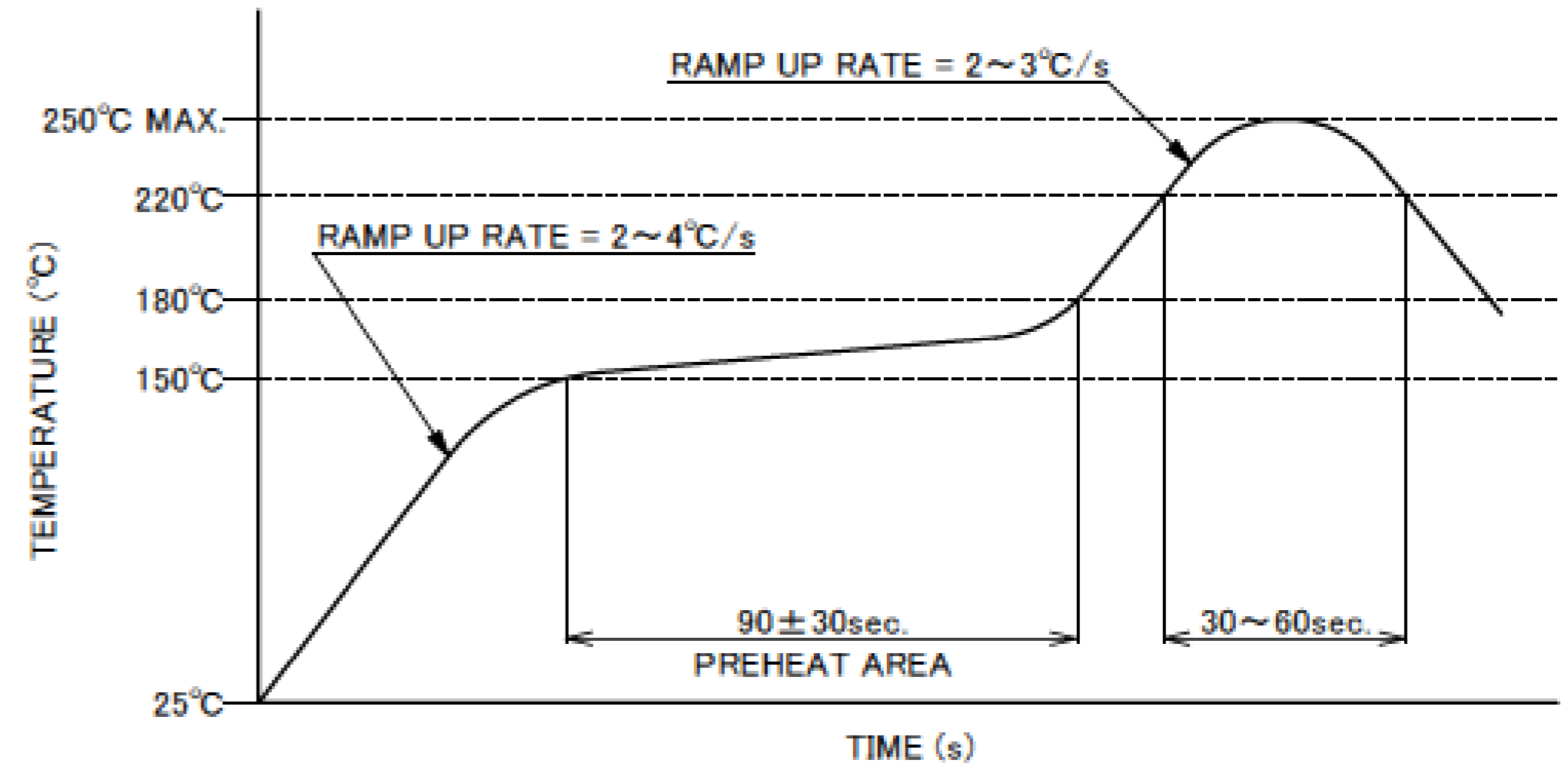
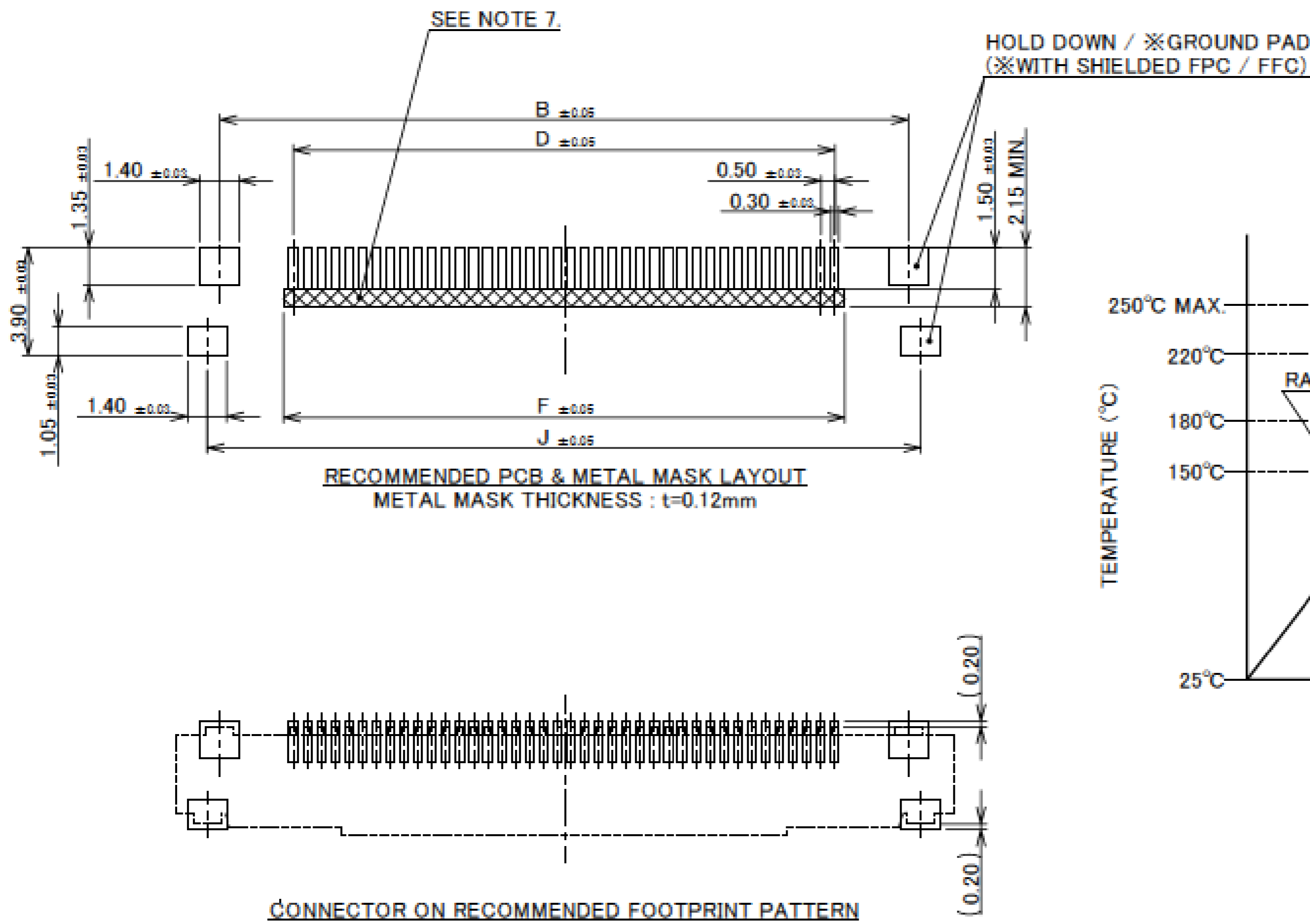
| NO. | COMPONENTS | MATERIAL | FINISH |
|-----|-----------------|---------------|--|
| 13 | SHIELD TAPE | METALLIC FILM | |
| 12 | INTERLAYER | ARBITRARY | |
| 11 | GROUND PLATE | METALLIC FILM | POLISH or HALF POLISH Sn PLATING |
| 10 | REINFORCED TAPE | ARBITRARY | |
| 9 | INSULATION FILM | ARBITRARY | |
| 8 | CONDUCTOR | COPPER ALLOY | CONTACT AREA : Au 0.05 μm MIN. OVER Ni 0.5 μm MIN. |



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Connector Assembly

| PART No. | B | D | F | J |
|---------------|-------|-------|-------|-------|
| 20799-020E-01 | 14.80 | 9.50 | 10.20 | 15.70 |
| 20799-030E-01 | 19.80 | 14.50 | 15.20 | 20.70 |
| 20799-040E-01 | 24.80 | 19.50 | 20.20 | 25.70 |
| 20799-050E-01 | 29.80 | 24.50 | 25.20 | 30.70 |
| 20799-060E-01 | 34.80 | 29.50 | 30.20 | 35.70 |



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

NOTES
7. SOLDER RESIST MUST BE APPLIED TO THIS AREA.

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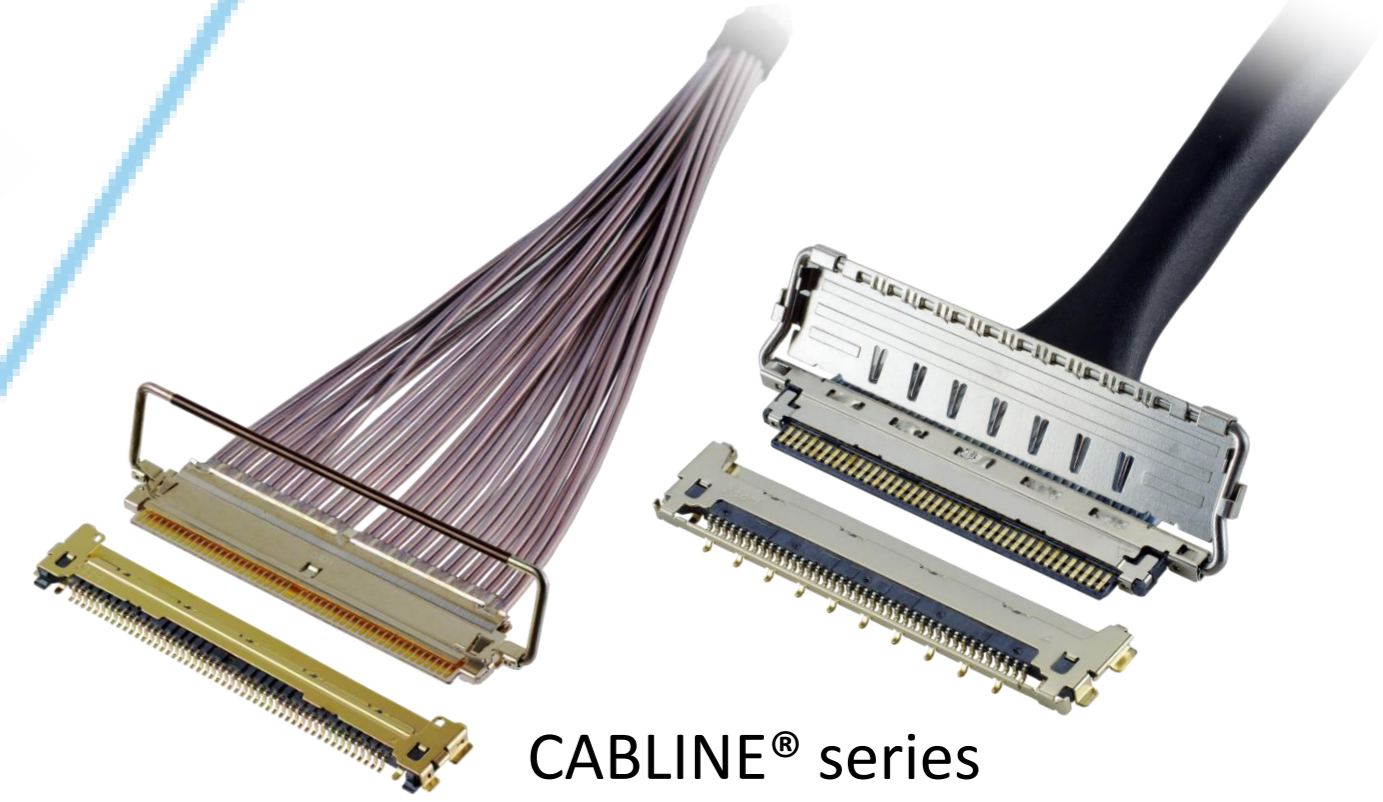
| ITEMS | SPECIFICATION |
|--|--|
| RATING VOLTAGE | 50V AC/DC (PER CONTACT PIN) |
| RATING AMPERAGE | 0.35A AC/DC (PER CONTACT PIN) AVAILABLE FOR ALL CONTACTS 0.5A AC/DC (PER CONTACT PIN) AVAILABLE UP TO 15 CONTACTS |
| OPERATING TEMPERATURE | 233~398K(-40°C~+125°C) |
| OPERATING HUMIDITY | 85% MAX. |
| CONTACT RESISTANCE | INITIAL : 60mohm MAX. / AFTER TEST : \triangleleft40mohm MAX. |
| INSULATION RESISTANCE | 500mohm MIN. |
| DIELECTRIC WITHSTANDING VOLTAGE | AC250V 1min |
| DURABILITY | 50TH CYCLES |
| FPC/FFC MATING FORCE (INITIAL / 50TH CYCLES) | 20P : 15.00 N MAX. 30P : 22.00 N MAX. 40P : 29.00 N MAX. 50P : 36.00 N MAX. 60P : 43.00 N MAX. |
| FPC/FFC UNMATING FORCE (INITIAL / 50TH CYCLES) | 20P : 2.00 N MIN. 30P : 2.70 N MIN. 40P : 3.40 N MIN. 50P : 4.10 N MIN. 60P : 4.80 N MIN. |
| FPC/FFC RETENTION FORCE (INITIAL / AFTER TEST) | 20P : 11.00 N MIN. 30P : 11.70 N MIN. 40P : 12.40 N MIN. 50P : 13.10 N MIN. 60P : 13.80 N MIN. |
| COPLANARITY | 0.10 MAX. |
| PRODUCT SPECIFICATION | PRS-2305 |
| TEST REPORT | TR-17100 |
| PACKING STANDARD | PST-18002 |
| INSTRUCTION MANUAL | HIM-16039 |
| APPEARANCE CRITERIA No. | QLS-A*** |

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Custom Connectors Available

 RF Connectors

MHF® series



CABLINE® series



Micro-coaxial/Twinax Connectors

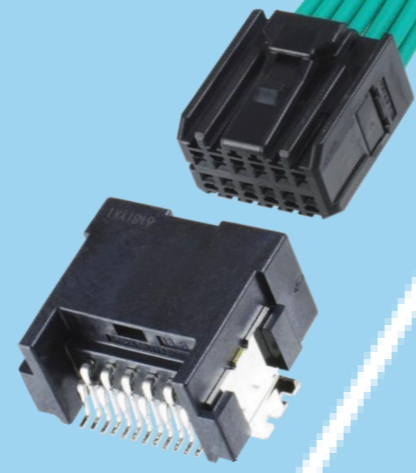


Wire-to-Board Connectors/Terminals

AP series



ISH® series



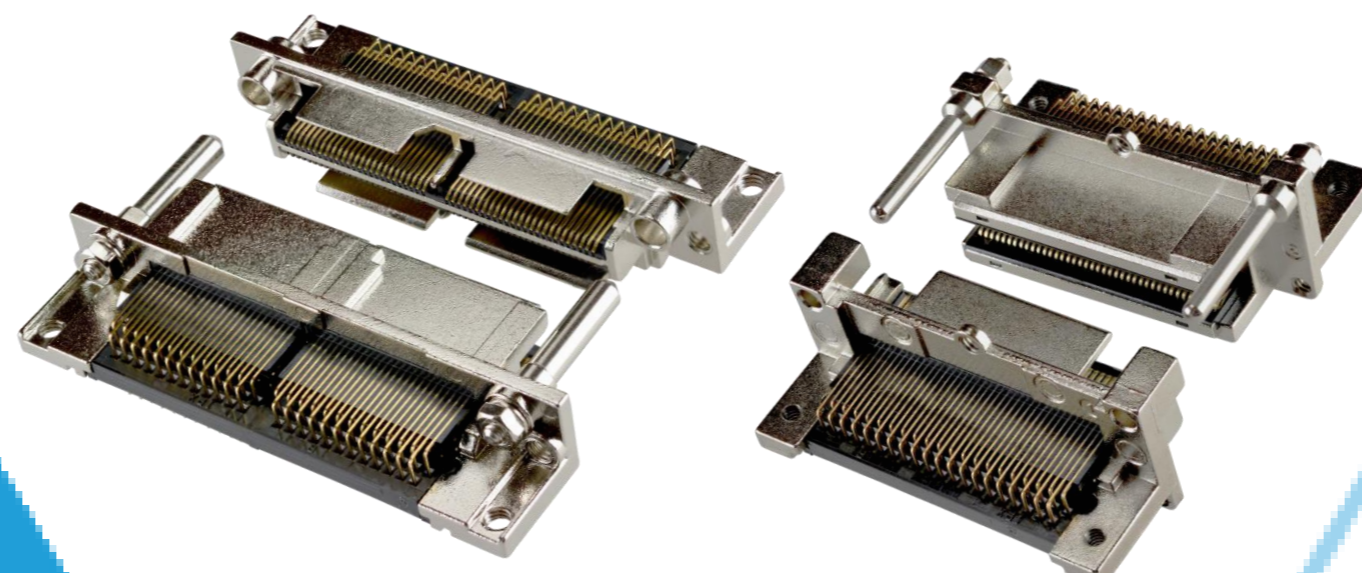
NOVASTACK® series



Board-to-Board Connectors



I/O Connectors



MINIDOCK™ series

MINIFLEX® series

EVAFLEX® series



FPC/FFC Connectors



Inquiry



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